



Material Content Data Sheet



Sales Product Name		BTS723GW		Issued		19. January 2018		
MA#		MA001427972						
Package		PG-DSO-14-37		Weight*		144.25 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.803	4.02	4.02	40229	40229
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		105	
	non noble metal	zinc	7440-66-6	0.060	0.04		418	
	non noble metal	iron	7439-89-6	1.207	0.84		8367	
wire	non noble metal	copper	7440-50-8	49.007	33.97	34.86	339744	348634
	noble metal	gold	7440-57-5	0.952	0.66	0.66	6600	6600
	encapsulation	organic material	carbon black	1333-86-4	0.167	0.12		1157
plastics	inorganic material	epoxy resin	-	7.677	5.32		53220	
		silicondioxide	60676-86-0	75.600	52.42	57.86	524100	578477
leadfinish	non noble metal	tin	7440-31-5	1.226	0.85	0.85	8500	8500
plating	noble metal	silver	7440-22-4	1.030	0.71	0.71	7139	7139
glue	plastics	epoxy resin	-	0.263	0.18		1824	
	noble metal	silver	7440-22-4	1.240	0.86	1.04	8597	10421
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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